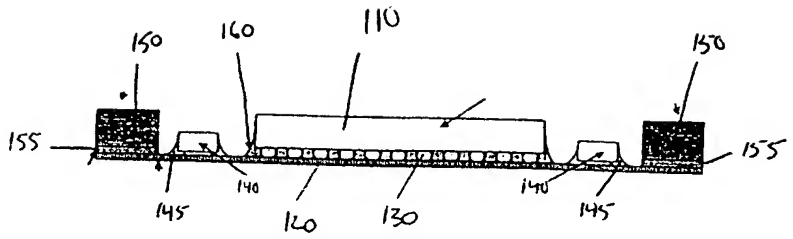

Figure 1 (Prior Art)

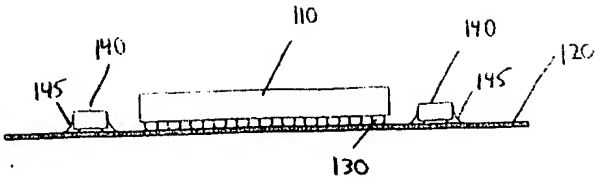

Figure 2a

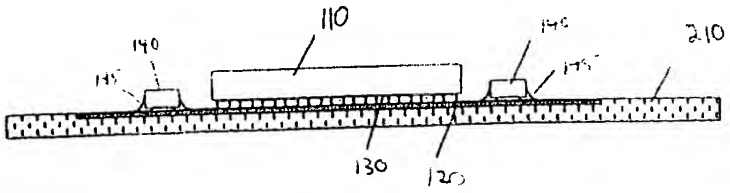

Figure 2b

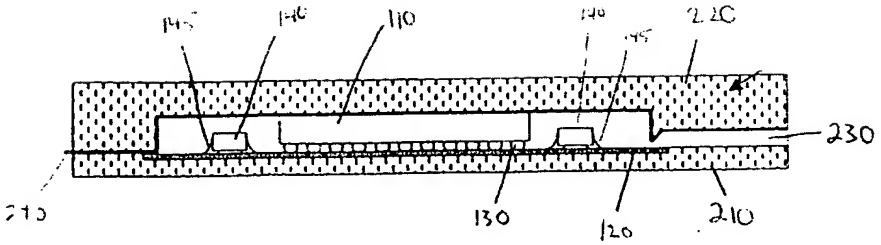

Figure 2c

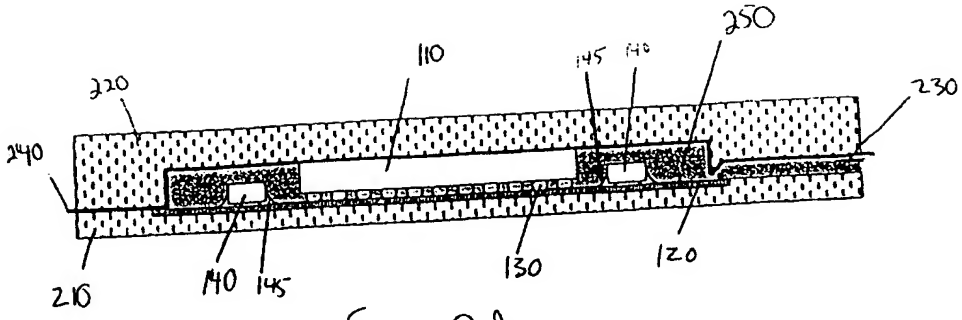

Figure 2d

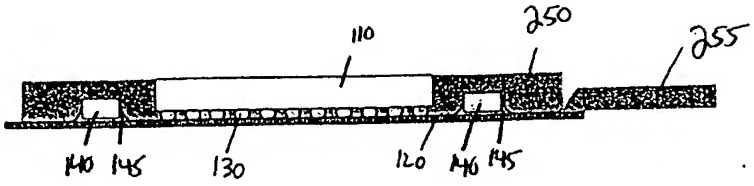

Figure 2e

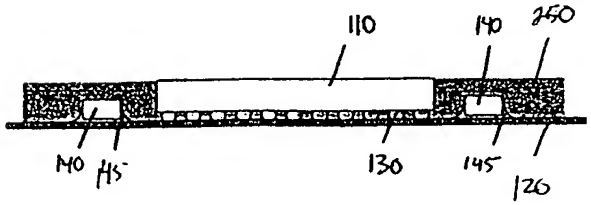

Figure 2f

Copy provided by USPTO

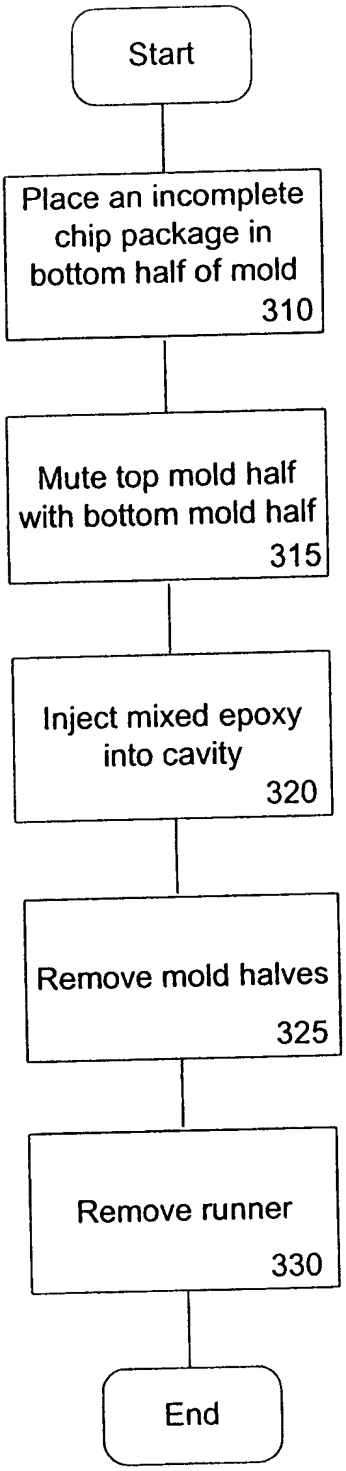
Start
Place an incomplete chip package in bottom half of mold
310
Mute top mold half with bottom mold half
315
Inject mixed epoxy into cavity
320
Remove mold halves
325
Remove runner
330
End

Figure 3